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Intel - EP20K1500EBC652-1 Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

2014.10	
Product Status	Obsolete
Number of LABs/CLBs	5184
Number of Logic Elements/Cells	51840
Total RAM Bits	442368
Number of I/O	488
Number of Gates	2392000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	652-BGA
Supplier Device Package	652-BGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k1500ebc652-1

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Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations

- Altera MegaCore[®] functions and Altera Megafunction Partners Program (AMPPSM) megafunctions
- NativeLink[™] integration with popular synthesis, simulation, and timing analysis tools
- Quartus II SignalTap[®] embedded logic analyzer simplifies in-system design evaluation by giving access to internal nodes during device operation
- Supports popular revision-control software packages including PVCS, Revision Control System (RCS), and Source Code Control System (SCCS)

 Table 4. APEX 20K QFP, BGA & PGA Package Options & I/O Count
 Notes (1), (2)

Device	144-Pin TQFP	208-Pin PQFP RQFP	240-Pin PQFP RQFP	356-Pin BGA	652-Pin BGA	655-Pin PGA
EP20K30E	92	125				
EP20K60E	92	148	151	196		
EP20K100	101	159	189	252		
EP20K100E	92	151	183	246		
EP20K160E	88	143	175	271		
EP20K200		144	174	277		
EP20K200E		136	168	271	376	
EP20K300E			152		408	
EP20K400					502	502
EP20K400E					488	
EP20K600E					488	
EP20K1000E					488	
EP20K1500E					488	

Cascade Chain

With the cascade chain, the APEX 20K architecture can implement functions with a very wide fan-in. Adjacent LUTs can compute portions of a function in parallel; the cascade chain serially connects the intermediate values. The cascade chain can use a logical AND or logical OR (via De Morgan's inversion) to connect the outputs of adjacent LEs. Each additional LE provides four more inputs to the effective width of a function, with a short cascade delay. Cascade chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry.

Cascade chains longer than ten LEs are implemented automatically by linking LABs together. For enhanced fitting, a long cascade chain skips alternate LABs in a MegaLAB structure. A cascade chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure. Figure 7 shows how the cascade function can connect adjacent LEs to form functions with a wide fan-in.



Figure 7. APEX 20K Cascade Chain

The counter mode uses two three-input LUTs: one generates the counter data, and the other generates the fast carry bit. A 2-to-1 multiplexer provides synchronous loading, and another AND gate provides synchronous clearing. If the cascade function is used by an LE in counter mode, the synchronous clear or load overrides any signal carried on the cascade chain. The synchronous clear overrides the synchronous load. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

Clear & Preset Logic Control

Logic for the register's clear and preset signals is controlled by LAB-wide signals. The LE directly supports an asynchronous clear function. The Quartus II software Compiler can use a NOT-gate push-back technique to emulate an asynchronous preset. Moreover, the Quartus II software Compiler can use a programmable NOT-gate push-back technique to emulate simultaneous preset and clear or asynchronous load. However, this technique uses three additional LEs per register. All emulation is performed automatically when the design is compiled. Registers that emulate simultaneous preset and load will enter an unknown state upon power-up or when the chip-wide reset is asserted.

In addition to the two clear and preset modes, APEX 20K devices provide a chip-wide reset pin (DEV_CLRn) that resets all registers in the device. Use of this pin is controlled through an option in the Quartus II software that is set before compilation. The chip-wide reset overrides all other control signals. Registers using an asynchronous preset are preset when the chip-wide reset is asserted; this effect results from the inversion technique used to implement the asynchronous preset.

FastTrack Interconnect

In the APEX 20K architecture, connections between LEs, ESBs, and I/O pins are provided by the FastTrack Interconnect. The FastTrack Interconnect is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

The FastTrack Interconnect consists of row and column interconnect channels that span the entire device. The row interconnect routes signals throughout a row of MegaLAB structures; the column interconnect routes signals throughout a column of MegaLAB structures. When using the row and column interconnect, an LE, IOE, or ESB can drive any other LE, IOE, or ESB in a device. See Figure 9.

Figure 11 shows the intersection of a row and column interconnect, and how these forms of interconnects and LEs drive each other.



Figure 11. Driving the FastTrack Interconnect

APEX 20KE devices include an enhanced interconnect structure for faster routing of input signals with high fan-out. Column I/O pins can drive the FastRow[™] interconnect, which routes signals directly into the local interconnect without having to drive through the MegaLAB interconnect. FastRow lines traverse two MegaLAB structures. Also, these pins can drive the local interconnect directly for fast setup times. On EP20K300E and larger devices, the FastRow interconnect drives the two MegaLABs in the top left corner, the two MegaLABs in the top right corner, the two MegaLABS in the bottom left corner, and the two MegaLABs in the bottom right corner. On EP20K200E and smaller devices, FastRow interconnect drives the two MegaLABs on the top and the two MegaLABs on the bottom of the device. On all devices, the FastRow interconnect drives all local interconnect in the appropriate MegaLABs except the local interconnect on the side of the MegaLAB opposite the ESB. Pins using the FastRow interconnect achieve a faster set-up time, as the signal does not need to use a MegaLAB interconnect line to reach the destination LE. Figure 12 shows the FastRow interconnect.

The programmable register also supports an asynchronous clear function. Within the ESB, two asynchronous clears are generated from global signals and the local interconnect. Each macrocell can either choose between the two asynchronous clear signals or choose to not be cleared. Either of the two clear signals can be inverted within the ESB. Figure 15 shows the ESB control logic when implementing product-terms.



Figure 15. ESB Product-Term Mode Control Logic

(1) APEX 20KE devices have four dedicated clocks.

Parallel Expanders

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 32 product terms to feed the macrocell OR logic directly, with two product terms provided by the macrocell and 30 parallel expanders provided by the neighboring macrocells in the ESB.

The Quartus II software Compiler can allocate up to 15 sets of up to two parallel expanders per set to the macrocells automatically. Each set of two parallel expanders incurs a small, incremental timing delay. Figure 16 shows the APEX 20K parallel expanders.





Embedded System Block

The ESB can implement various types of memory blocks, including dual-port RAM, ROM, FIFO, and CAM blocks. The ESB includes input and output registers; the input registers synchronize writes, and the output registers can pipeline designs to improve system performance. The ESB offers a dual-port mode, which supports simultaneous reads and writes at two different clock frequencies. Figure 17 shows the ESB block diagram.







Figure 18. Deep Memory Block Implemented with Multiple ESBs

The ESB implements two forms of dual-port memory: read/write clock mode and input/output clock mode. The ESB can also be used for bidirectional, dual-port memory applications in which two ports read or write simultaneously. To implement this type of dual-port memory, two or four ESBs are used to support two simultaneous reads or writes. This functionality is shown in Figure 19.





For more information on APEX 20KE devices and CAM, see *Application* Note 119 (Implementing High-Speed Search Applications with APEX CAM).

Driving Signals to the ESB

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnect can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and asynchronous clear signals. Figure 24 shows the ESB control signal generation logic.





(1) APEX 20KE devices have four dedicated clocks.

An ESB is fed by the local interconnect, which is driven by adjacent LEs (for high-speed connection to the ESB) or the MegaLAB interconnect. The ESB can drive the local, MegaLAB, or FastTrack Interconnect routing structure to drive LEs and IOEs in the same MegaLAB structure or anywhere in the device.

Advanced I/O Standard Support

APEX 20KE IOEs support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.



For more information on I/O standards supported by APEX 20KE devices, see *Application Note* 117 (*Using Selectable I/O Standards in Altera Devices*).

The APEX 20KE device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a particular bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K300E and larger APEX 20KE devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K300E and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400E devices and larger with an X-suffix on the ordering code add a serializer/deserializer circuit and PLL for higher-speed support.

Each bank can support multiple standards with the same VCCIO for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same VCCIO voltage level. For example, when VCCIO is 3.3 V, a bank can support LVTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used as LVDS I/O banks, they support all of the other I/O standards. Figure 29 shows the arrangement of the APEX 20KE I/O banks.

APEX 20KE devices also support the MultiVolt I/O interface feature. The APEX 20KE VCCINT pins must always be connected to a 1.8-V power supply. With a 1.8-V V_{CCINT} level, input pins are 1.8-V, 2.5-V, and 3.3-V tolerant. The VCCIO pins can be connected to either a 1.8-V, 2.5-V, or 3.3-V power supply, depending on the I/O standard requirements. When the VCCIO pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When VCCIO pins are connected to a 3.3-V power supply, the output levels are sometime with 2.5-V systems. When VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and compatible with 3.3-V or 5.0-V systems. An APEX 20KE device is 5.0-V tolerant with the addition of a resistor.

Table 13 summarizes APEX 20KE MultiVolt I/O support.

Table 13. /	Table 13. APEX 20KE MultiVolt I/O Support Note (1)											
V _{CCIO} (V)		Input Siç	jnals (V)			Output S	ignals (V)					
	1.8	2.5	3.3	5.0	1.8	2.5	3.3	5.0				
1.8	\checkmark	\checkmark	\checkmark		\checkmark							
2.5	\checkmark	\checkmark	>			\checkmark						
3.3	\checkmark	\checkmark	\checkmark	(2)			✓(3)					

Notes to Table 13:

 The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}, except for the 5.0-V input case.

(2) An APEX 20KE device can be made 5.0-V tolerant with the addition of an external resistor. You also need a PCI clamp and series resistor.

(3) When V_{CCIO} = 3.3 V, an APEX 20KE device can drive a 2.5-V device with 3.3-V tolerant inputs.

ClockLock & ClockBoost Features

APEX 20K devices support the ClockLock and ClockBoost clock management features, which are implemented with PLLs. The ClockLock circuitry uses a synchronizing PLL that reduces the clock delay and skew within a device. This reduction minimizes clock-to-output and setup times while maintaining zero hold times. The ClockBoost circuitry, which provides a clock multiplier, allows the designer to enhance device area efficiency by sharing resources within the device. The ClockBoost circuitry allows the designer to distribute a low-speed clock and multiply that clock on-device. APEX 20K devices include a high-speed clock tree; unlike ASICs, the user does not have to design and optimize the clock tree. The ClockLock and ClockBoost features work in conjunction with the APEX 20K device's high-speed clock to provide significant improvements in system performance and band-width. Devices with an X-suffix on the ordering code include the ClockLock circuit.

The ClockLock and ClockBoost features in APEX 20K devices are enabled through the Quartus II software. External devices are not required to use these features.

Table 22 shows the JTAG timing parameters and values for APEX 20K devices.

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Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		35	ns
t _{JSZX}	Update register high impedance to valid output		35	ns
t _{JSXZ}	Update register valid output to high impedance		35	ns

Table 22. APEX 20K JTAG Timing Parameters & Values

For more information, see the following documents:

- Application Note 39 (IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)
- Jam Programming & Test Language Specification

Generic Testing

Each APEX 20K device is functionally tested. Complete testing of each configurable static random access memory (SRAM) bit and all logic functionality ensures 100% yield. AC test measurements for APEX 20K devices are made under conditions equivalent to those shown in Figure 32. Multiple test patterns can be used to configure devices during all stages of the production flow.

Table 39. APEX	20KE External Bidirectional Timing Parameters Note (1)	
Symbol	Parameter	Conditions
t _{INSUBIDIR}	Setup time for bidirectional pins with global clock at LAB adjacent Input Register	
t _{INHBIDIR}	Hold time for bidirectional pins with global clock at LAB adjacent Input Register	
^t OUTCOBIDIR	Clock-to-output delay for bidirectional pins with global clock at IOE output register	C1 = 10 pF
t _{XZBIDIR}	Synchronous Output Enable Register to output buffer disable delay	C1 = 10 pF
t _{ZXBIDIR}	Synchronous Output Enable Register output buffer enable delay	C1 = 10 pF
t _{INSUBIDIRPLL}	Setup time for bidirectional pins with PLL clock at LAB adjacent Input Register	
t _{INHBIDIRPLL}	Hold time for bidirectional pins with PLL clock at LAB adjacent Input Register	
^t OUTCOBIDIRPLL	Clock-to-output delay for bidirectional pins with PLL clock at IOE output register	C1 = 10 pF
t _{XZBIDIRPLL}	Synchronous Output Enable Register to output buffer disable delay with PLL	C1 = 10 pF
t _{ZXBIDIRPLL}	Synchronous Output Enable Register output buffer enable delay with PLL	C1 = 10 pF

Note to Tables 38 and 39:

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(1) These timing parameters are sample-tested only.

Tables 55 through 60 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K60E APEX 20KE devices.

Table 55. EP20K60E f _{MAX} LE Timing Microparameters										
Symbol		-1		-2		.3	Unit			
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.17		0.15		0.16		ns			
t _H	0.32		0.33		0.39		ns			
t _{CO}		0.29		0.40		0.60	ns			
t _{LUT}		0.77		1.07		1.59	ns			

Table 57. EP20K60E f _{MAX} Routing Delays										
Symbol		-1 -2		-	-3					
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.24		0.26		0.30	ns			
t _{F5-20}		1.45		1.58		1.79	ns			
t _{F20+}		1.96		2.14		2.45	ns			

Table 58. EP.	Table 58. EP20K60E Minimum Pulse Width Timing Parameters										
Symbol	-	1	-	2	-3	}	Unit				
	Min	Max	Min	Max	Min	Max					
t _{CH}	2.00		2.50		2.75		ns				
t _{CL}	2.00		2.50		2.75		ns				
t _{CLRP}	0.20		0.28		0.41		ns				
t _{PREP}	0.20		0.28		0.41		ns				
t _{ESBCH}	2.00		2.50		2.75		ns				
t _{ESBCL}	2.00		2.50		2.75		ns				
t _{ESBWP}	1.29		1.80		2.66		ns				
t _{ESBRP}	1.04		1.45		2.14		ns				

Table 59. EP20K60E External Timing Parameters										
Symbol	-1			-2	-3	}	Unit			
	Min	Max	Min	Max	Min	Max				
t _{INSU}	2.03		2.12		2.23		ns			
t _{INH}	0.00		0.00		0.00		ns			
t _{outco}	2.00	4.84	2.00	5.31	2.00	5.81	ns			
tinsupll	1.12		1.15		-		ns			
t _{INHPLL}	0.00		0.00		-		ns			
t _{outcopll}	0.50	3.37	0.50	3.69	-	-	ns			

Table 64. EP2	Table 64. EP20K100E Minimum Pulse Width Timing Parameters									
Symbol	-	1	-	2	-:	3	Unit			
	Min	Max	Min	Max	Min	Max				
t _{CH}	2.00		2.00		2.00		ns			
t _{CL}	2.00		2.00		2.00		ns			
t _{CLRP}	0.20		0.20		0.20		ns			
t _{PREP}	0.20		0.20		0.20		ns			
t _{ESBCH}	2.00		2.00		2.00		ns			
t _{ESBCL}	2.00		2.00		2.00		ns			
t _{ESBWP}	1.29		1.53		1.66		ns			
t _{ESBRP}	1.11		1.29		1.41		ns			

Table 65. EP2	Table 65. EP20K100E External Timing Parameters										
Symbol	-	1		-2	-3	-3					
	Min	Max	Min	Max	Min	Max					
t _{INSU}	2.23		2.32		2.43		ns				
t _{INH}	0.00		0.00		0.00		ns				
t _{outco}	2.00	4.86	2.00	5.35	2.00	5.84	ns				
t _{INSUPLL}	1.58		1.66		-		ns				
t _{INHPLL}	0.00		0.00		-		ns				
t _{outcopll}	0.50	2.96	0.50	3.29	-	-	ns				

Table 66. EP20K100E External Bidirectional Timing Parameters									
Symbol	-	1	-	2	-	-3	Unit		
	Min	Max	Min	Max	Min	Max			
t _{insubidir}	2.74		2.96		3.19		ns		
t _{inhbidir}	0.00		0.00		0.00		ns		
t _{outcobidir}	2.00	4.86	2.00	5.35	2.00	5.84	ns		
t _{XZBIDIR}		5.00		5.48		5.89	ns		
t _{ZXBIDIR}		5.00		5.48		5.89	ns		
t _{insubidirpll}	4.64		5.03		-		ns		
t _{inhbidirpll}	0.00		0.00		-		ns		
t _{outcobidirpll}	0.50	2.96	0.50	3.29	-	-	ns		
t _{xzbidirpll}		3.10		3.42		-	ns		
t _{ZXBIDIRPLL}		3.10		3.42		-	ns		

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Table 86. EP20k	Table 86. EP20K400E f _{MAX} ESB Timing Microparameters										
Symbol	-1 Speed Grade		-2 Spe	-2 Speed Grade		-3 Speed Grade					
	Min	Max	Min	Max	Min	Max					
t _{ESBARC}		1.67		1.91		1.99	ns				
t _{ESBSRC}		2.30		2.66		2.93	ns				
t _{ESBAWC}		3.09		3.58		3.99	ns				
t _{ESBSWC}		3.01		3.65		4.05	ns				
t _{ESBWASU}	0.54		0.63		0.65		ns				
t _{ESBWAH}	0.36		0.43		0.42		ns				
t _{ESBWDSU}	0.69		0.77		0.84		ns				
t _{ESBWDH}	0.36		0.43		0.42		ns				
t _{ESBRASU}	1.61		1.77		1.86		ns				
t _{ESBRAH}	0.00		0.00		0.01		ns				
t _{ESBWESU}	1.35		1.47		1.61		ns				
t _{ESBWEH}	0.00		0.00		0.00		ns				
t _{ESBDATASU}	-0.18		-0.30		-0.27		ns				
t _{ESBDATAH}	0.13		0.13		0.13		ns				
t _{ESBWADDRSU}	-0.02		-0.11		-0.03		ns				
t _{ESBRADDRSU}	0.06		-0.01		-0.05		ns				
t _{ESBDATACO1}		1.16		1.40		1.54	ns				
t _{ESBDATACO2}		2.18		2.55		2.85	ns				
t _{ESBDD}		2.73		3.17		3.58	ns				
t _{PD}		1.57		1.83		2.07	ns				
t _{PTERMSU}	0.92		0.99		1.18		ns				
t _{PTERMCO}		1.18		1.43		1.17	ns				

Table 94. EP20K600E Minimum Pulse Width Timing Parameters											
Symbol	-1 Spee	d Grade	-2 Spee	d Grade	-3 Speed	l Grade	Unit				
	Min	Max	Min	Max	Min	Max					
t _{CH}	2.00		2.50		2.75		ns				
t _{CL}	2.00		2.50		2.75		ns				
t _{CLRP}	0.18		0.26		0.34		ns				
t _{PREP}	0.18		0.26		0.34		ns				
t _{ESBCH}	2.00		2.50		2.75		ns				
t _{ESBCL}	2.00		2.50		2.75		ns				
t _{ESBWP}	1.17		1.68		2.18		ns				
t _{ESBRP}	0.95		1.35		1.76		ns				

Table 95. EP20K600E External Timing Parameters											
Symbol	-1 Spee	d Grade	-2 Spee	ed Grade	-3 Spee	-3 Speed Grade					
	Min	Max	Min	Max	Min	Max					
t _{INSU}	2.74		2.74		2.87		ns				
t _{INH}	0.00		0.00		0.00		ns				
tоитсо	2.00	5.51	2.00	6.06	2.00	6.61	ns				
tINSUPLL	1.86		1.96		-		ns				
t _{INHPLL}	0.00		0.00		-		ns				
toutcopll	0.50	2.62	0.50	2.91	-	-	ns				

Table 96. EP20K600E External Bidirectional Timing Parameters										
Symbol	-1 Spee	d Grade	-2 Spee	d Grade	-3 Speed Grade		Unit			
	Min	Max	Min	Мах	Min	Max	1			
t _{insubidir}	0.64		0.98		1.08		ns			
t _{inhbidir}	0.00		0.00		0.00		ns			
t _{outcobidir}	2.00	5.51	2.00	6.06	2.00	6.61	ns			
t _{XZBIDIR}		6.10		6.74		7.10	ns			
t _{ZXBIDIR}		6.10		6.74		7.10	ns			
t _{insubidirpll}	2.26		2.68		-		ns			
t _{inhbidirpll}	0.00		0.00		-		ns			
t _{outcobidirpll}	0.50	2.62	0.50	2.91	-	-	ns			
t _{XZBIDIRPLL}		3.21		3.59		-	ns			
t _{ZXBIDIRPLL}		3.21		3.59		-	ns			

Table 98. EP20K1000E f _{MAX} ESB Timing Microparameters										
Symbol	-1 Speed Grade		-2 Spe	-2 Speed Grade		-3 Speed Grade				
	Min	Max	Min	Max	Min	Max				
t _{ESBARC}		1.78		2.02		1.95	ns			
t _{ESBSRC}		2.52		2.91		3.14	ns			
t _{ESBAWC}		3.52		4.11		4.40	ns			
t _{ESBSWC}		3.23		3.84		4.16	ns			
t _{ESBWASU}	0.62		0.67		0.61		ns			
t _{ESBWAH}	0.41		0.55		0.55		ns			
t _{ESBWDSU}	0.77		0.79		0.81		ns			
t _{ESBWDH}	0.41		0.55		0.55		ns			
t _{ESBRASU}	1.74		1.92		1.85		ns			
t _{ESBRAH}	0.00		0.01		0.23		ns			
t _{ESBWESU}	2.07		2.28		2.41		ns			
t _{ESBWEH}	0.00		0.00		0.00		ns			
t _{ESBDATASU}	0.25		0.27		0.29		ns			
t _{ESBDATAH}	0.13		0.13		0.13		ns			
t _{ESBWADDRSU}	0.11		0.04		0.11		ns			
t _{ESBRADDRSU}	0.14		0.11		0.16		ns			
t _{ESBDATACO1}		1.29		1.50		1.63	ns			
t _{ESBDATACO2}		2.55		2.99		3.22	ns			
t _{ESBDD}		3.12		3.57		3.85	ns			
t _{PD}		1.84		2.13		2.32	ns			
t _{PTERMSU}	1.08		1.19		1.32		ns			
t _{PTERMCO}		1.31		1.53		1.66	ns			

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Table 102. EP20K1000E External Bidirectional Timing Parameters										
Symbol	-1 Spee	ed Grade	-2 Spee	d Grade	-3 Spec	ed Grade	Unit			
	Min	Max	Min	Max	Min	Max				
t _{insubidir}	3.22		3.33		3.51		ns			
t _{inhbidir}	0.00		0.00		0.00		ns			
toutcobidir	2.00	5.75	2.00	6.33	2.00	6.90	ns			
t _{XZBIDIR}		6.31		7.09		7.76	ns			
t _{ZXBIDIR}		6.31		7.09		7.76	ns			
t _{INSUBIDIRPL} L	3.25		3.26				ns			
t _{inhbidirpll}	0.00		0.00				ns			
t _{outcobidirpll}	0.50	2.25	0.50	2.99			ns			
t _{XZBIDIRPLL}		2.81		3.80			ns			
t _{ZXBIDIRPLL}		2.81		3.80			ns			

Tables 103 through 108 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K1500E APEX 20KE devices.

Table 103. EP20K1500E f _{MAX} LE Timing Microparameters										
Symbol	-1 Spee	d Grade	-2 Spee	ed Grade	-3 Spee	Unit				
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.25		0.25		0.25		ns			
t _H	0.25		0.25		0.25		ns			
t _{CO}		0.28		0.32		0.33	ns			
t _{LUT}		0.80		0.95		1.13	ns			

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Revision History

The information contained in the *APEX 20K Programmable Logic Device Family Data Sheet* version 5.1 supersedes information published in previous versions.

Version 5.1

APEX 20K Programmable Logic Device Family Data Sheet version 5.1 contains the following changes:

- In version 5.0, the VI input voltage spec was updated in Table 28 on page 63.
- In version 5.0, *Note* (5) to Tables 27 through 30 was revised.
- Added *Note* (2) to Figure 21 on page 33.

Version 5.0

APEX 20K Programmable Logic Device Family Data Sheet version 5.0 contains the following changes:

- Updated Tables 23 through 26. Removed 2.5-V operating condition tables because all APEX 20K devices are now 5.0-V tolerant.
- Updated conditions in Tables 33, 38 and 39.
- Updated data for t_{ESBDATAH} parameter.

Version 4.3

APEX 20K Programmable Logic Device Family Data Sheet version 4.3 contains the following changes:

- Updated Figure 20.
- Updated *Note* (2) to Table 13.
- Updated notes to Tables 27 through 30.

Version 4.2

APEX 20K Programmable Logic Device Family Data Sheet version 4.2 contains the following changes:

- Updated Figure 29.
- Updated *Note* (1) to Figure 29.